# 2SK1809

# Silicon N-Channel MOS FET

# **HITACHI**

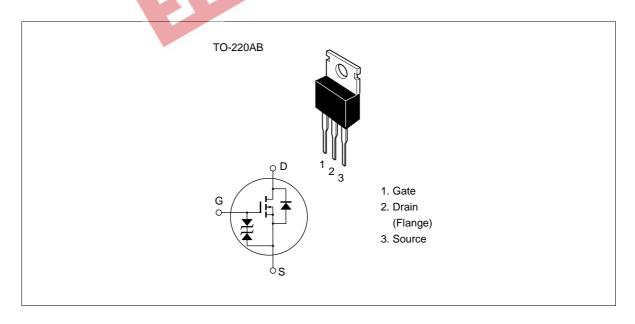
## **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- 逐步<sup>表现。</sup>Cn Suitable for switchingregulator, DC-DC converter

### **Outline**





## 2SK1809

### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit				
Drain to source voltage	V <sub>DSS</sub>	600	V				
Gate to source voltage	$V_{\rm GSS}$	±30	V				
Drain current	I <sub>D</sub>	5	A				
Drain peak current	I <sub>D(pulse)</sub> *1	20	A				
Body to drain diode reverse drain current	$I_{DR}$	5	Α				
Channel dissipation	Pch*2	60	W				
Channel temperature	Tch	150	°C				
Storage temperature	Tstg	-55 to +150	°C				
Notes 1. PW ≤ 10 µs, duty cycle ≤ 1 % 2. Value at Tc = 25 °C							



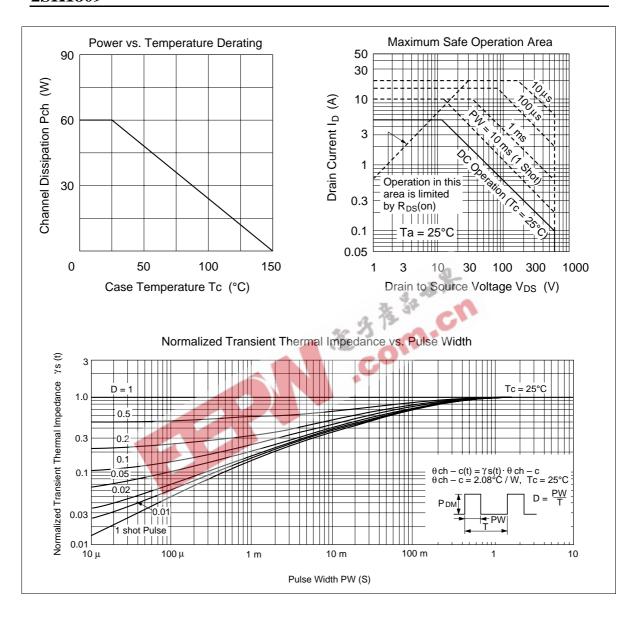
# **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

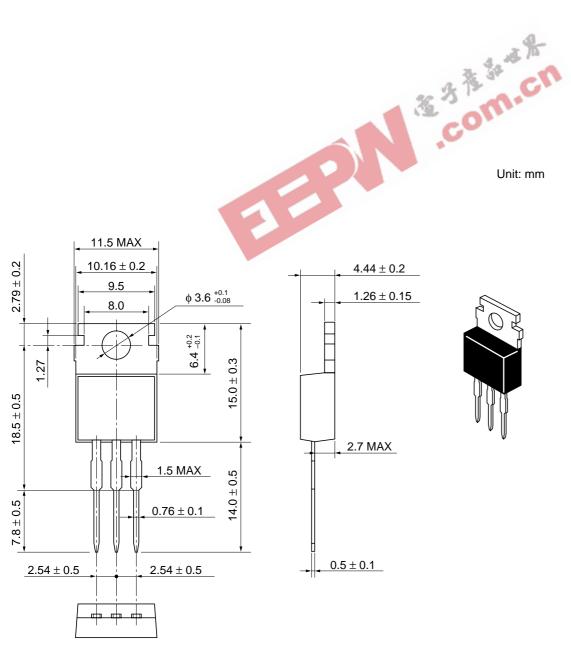
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	600	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R <sub>DS(on)</sub>	_	1.1	1.5	Ω	$I_D = 2.5A$ $V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	y <sub>fs</sub>	3.0	5.0	_	S	$I_{D} = 2.5 \text{ A}$ $V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1000	- 25c	pF	V <sub>DS</sub> = 10 V
Output capacitance	Coss	_	250	女作	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	-	45	i- "	pF	f = 1 MHz
Turn-on delay time	t <sub>d(on)</sub>		12	0	ns	I <sub>D</sub> = 2.5 A
Rise time	t,	71	45		ns	V <sub>GS</sub> = 10 V
Turn-off delay time	t <sub>d(off)</sub>	7.3	105	_	ns	$R_L = 12 \Omega$
Fall time	t <sub>f</sub>		55	_	ns	_
Body to drain diode forward voltage	$V_{DF}$	_	0.9	_	V	$I_F = 5 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>		500	_	ns	$I_F = 5 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

Note 1. Pulse Test

See characteristic curves of 2SK1404

# 2SK1809





Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1 8 a

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